

AMOLEDs

High Power LED

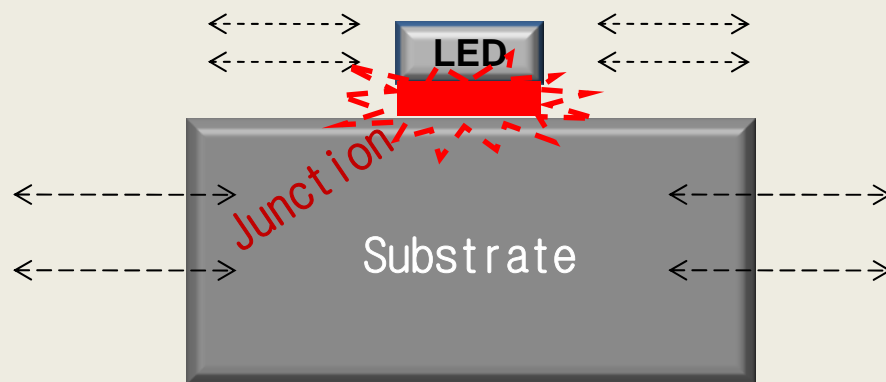
Lighting Application

Ceramic

- Robust material against harsh environment
- High Reliability due to thermal stability
- TCE matching with LED die
- The best material for high power LED
- Ceramic LED should be the best option
for reliable lighting application

Why TCE ?

- TCE (Thermal Coefficient of Expansion)
- TCE mismatch causes most defects in Junction area when it's heated and cooled.
- Ceramic is perfectly matched to LED die
- No defects in Junction area
- It guarantees long life time



Material	CTE (ppm/°C)
Plastic	66
Cu	16.4
HTCC	7.00
LTCC	7.2

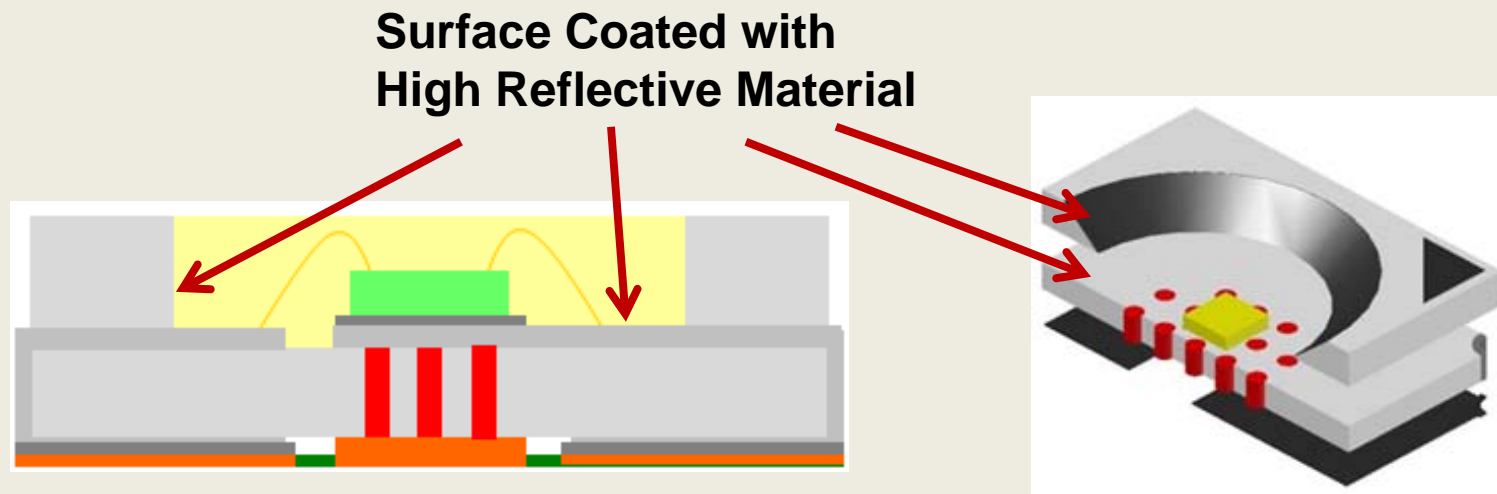
AMOLEDs High Power LED

Advantage

- Design for High lumen output, efficacy
- Thermal management
 - Specially designed structures
- Various distribution beam angle
 - 30 ~ 160 degree without additional optics
 - Design flexibility
- Long life time with lumen maintenance
- High Power Multichip package
 - Optimized material & structure

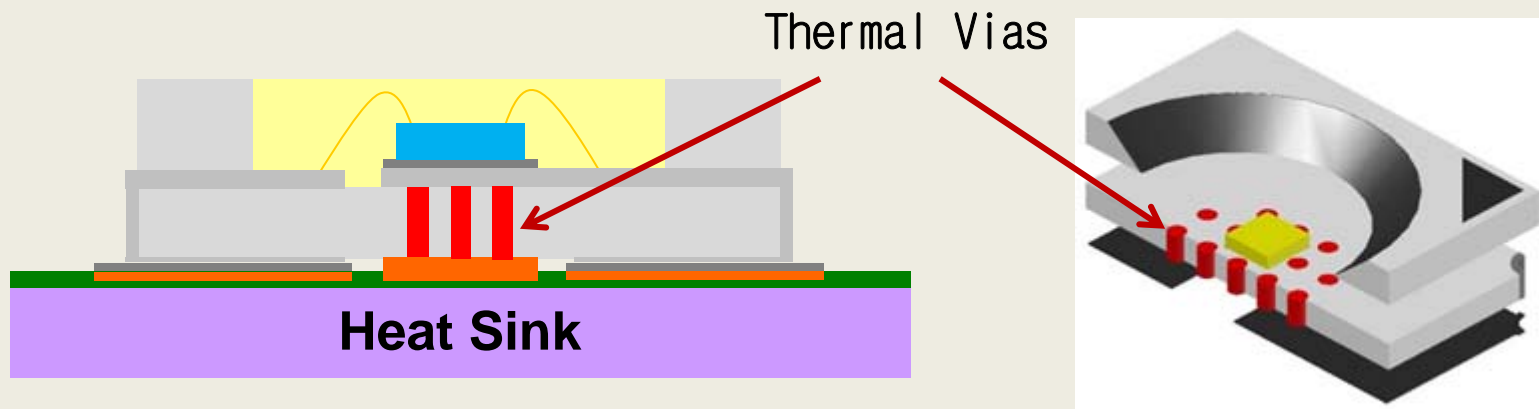
Package Structure

- Higher Lumen Output Design
 - Surface coated with special material
 - Efficacy : $> 90 \text{ lm/W}$
 - Excellent Lumen Maintenance



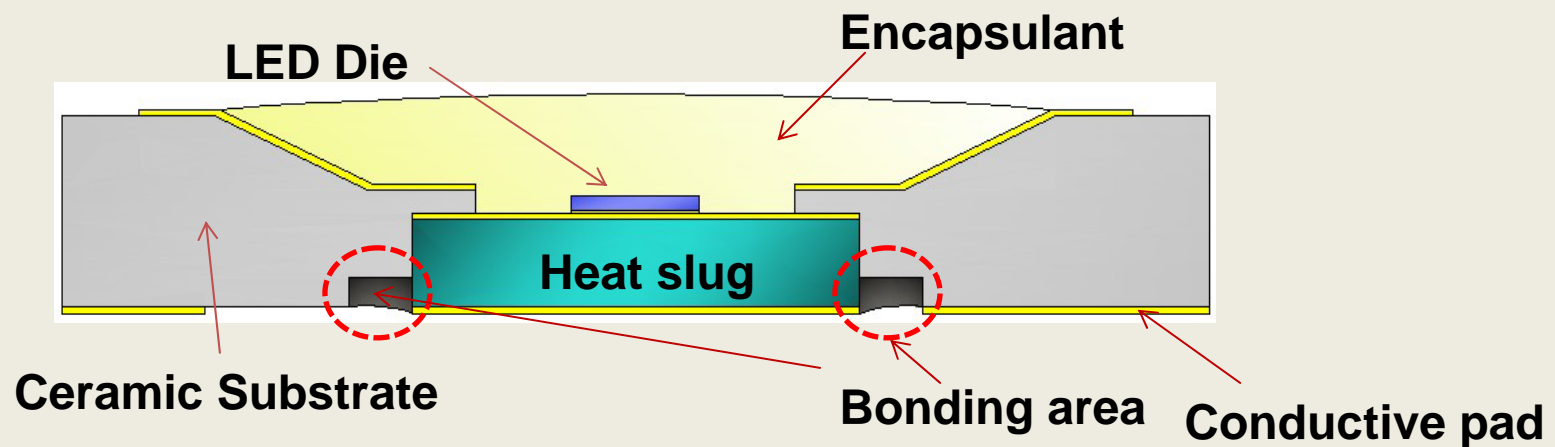
Package Structure

- Thermal Management I
- Thermal Via Structure
 - Several Vias filled with conductor material
 - Heat flows down to heat sink through Vias
 - Thermal Resistance : $10\text{ }^{\circ}\text{C/W}$



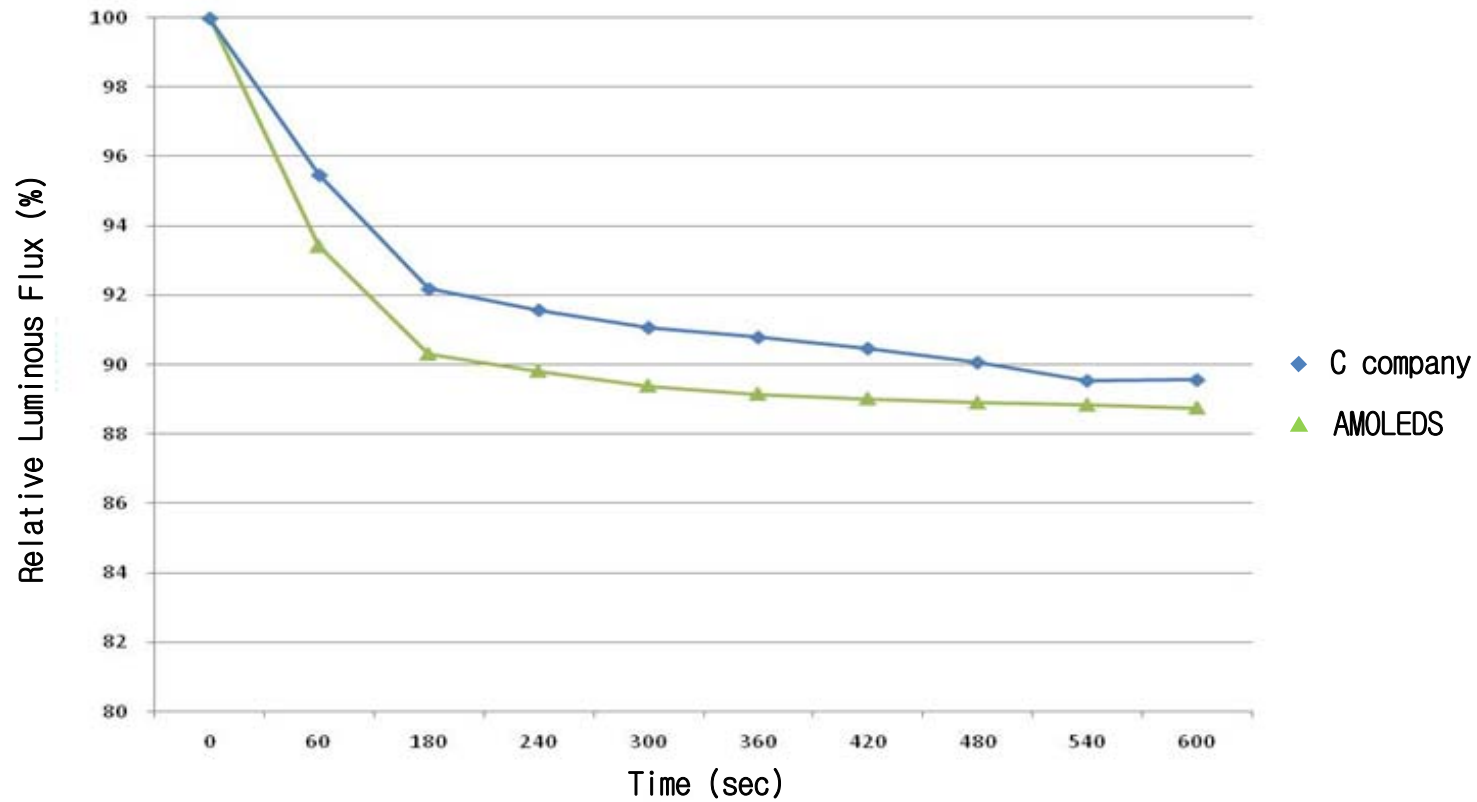
Package Structure

- Thermal Management II
- Heat Slug Structure
 - The best option for high power LED
 - TCE matched heat slug material
 - Thermal Resistance : 8 °C/W



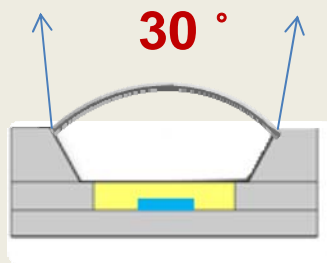
Saturation Curve

- Condition : 350 mA, on Star MCPCB (20 ϕ)

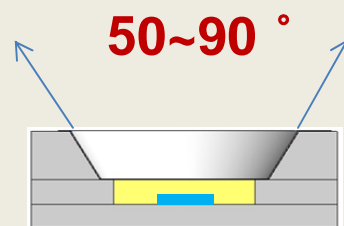


Package Structure

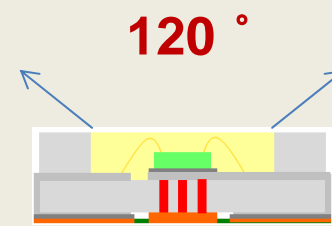
- Various Beam Angle Structures
 - Reflector Embedded
 - Reflector angle, depth, reflectivity control
 - 30 ~ 160 degree without additional lens
- Several options for light design



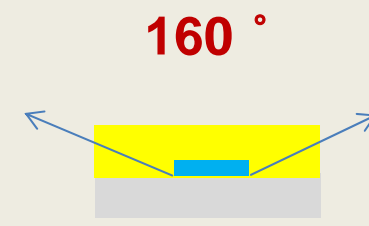
New Product



Embedded Reflector



Standard



Wide Beam

Standard Product

Model	Power (W)	Current (mA)	Luminous flux (lm)	CCT (K)	Beam angle (Degree)
AL-3030	0.5	150	45	2750~10,000	120
AL-5050	1	350	90	2750~10,000	120
AL-7090	1~3	350~700	90~160	2750~10,000	120

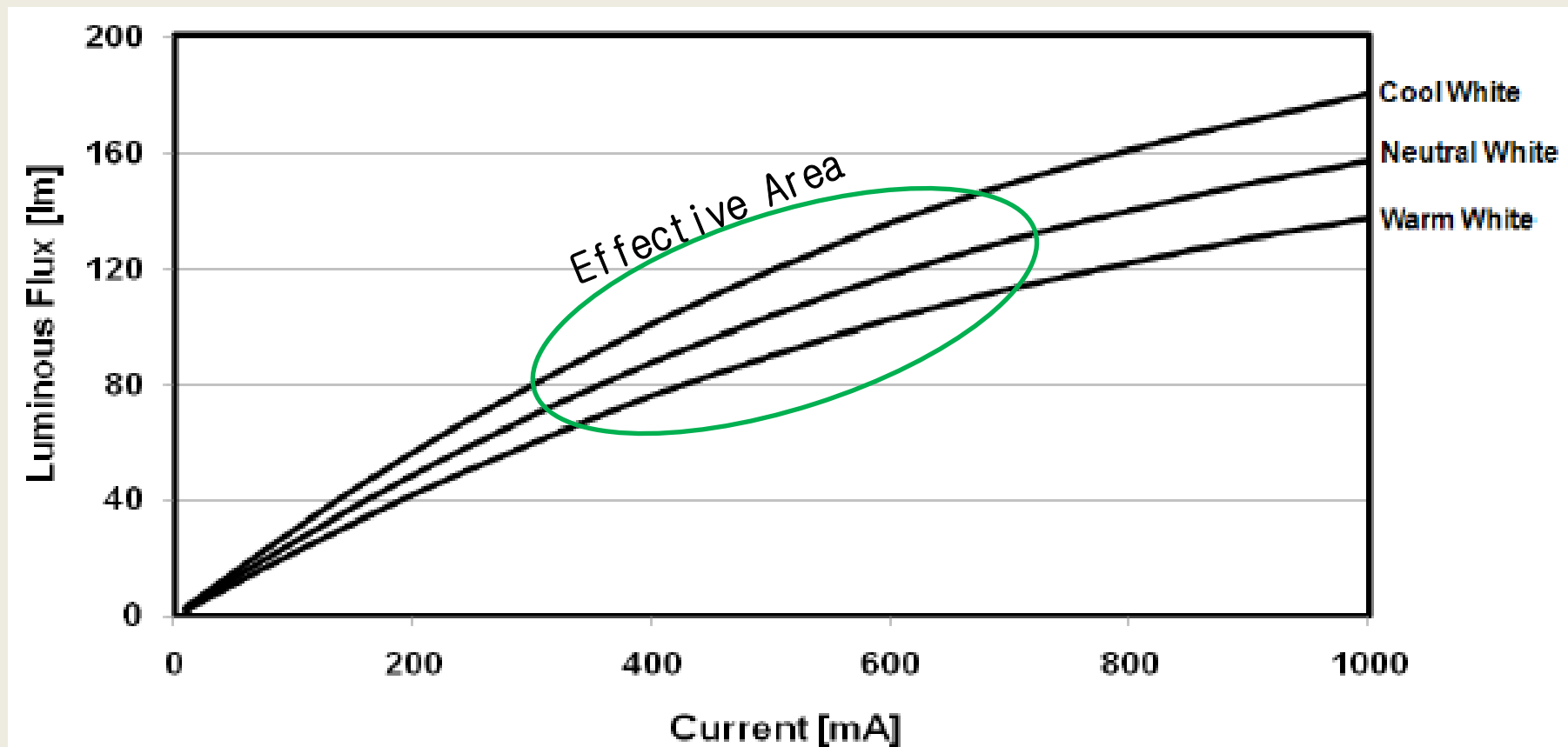
Advantage

- High Efficacy
- Thermal Stability
- Long life time
- Easy to array



Efficacy Diagram

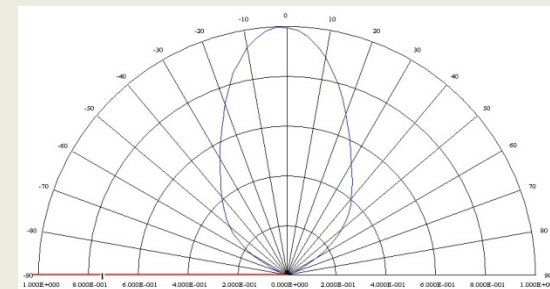
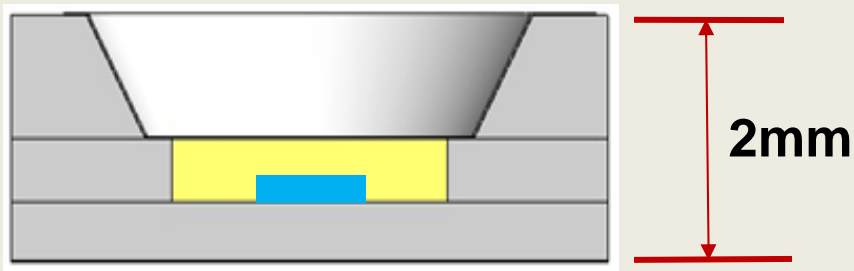
- Model : AL-7090
- Luminous Flux according to current up to 1000 mA



Narrow Beam Angle Product

- Beam Angle
 - 50 ~ 90 degree without lens
 - Compact 2 mm thickness
 - Patented structure
- Design Flexibility due to low profile
- Spot light, Street light without lens

AL-WH505020

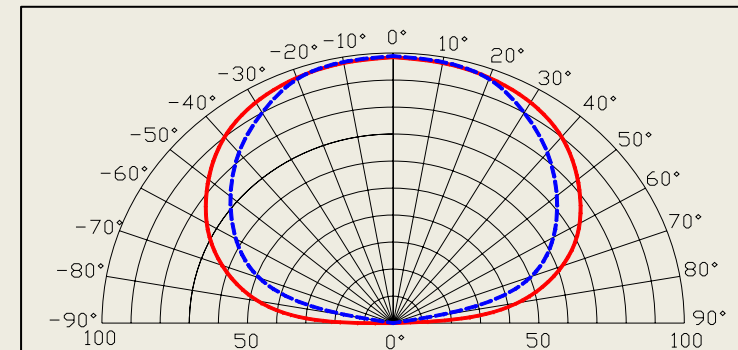
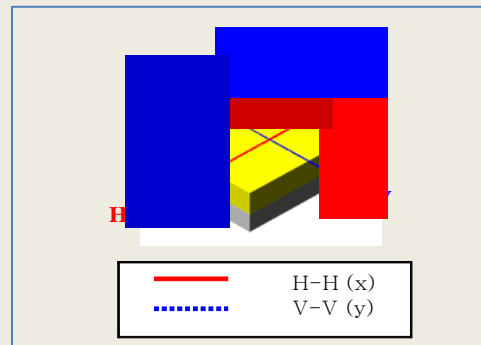
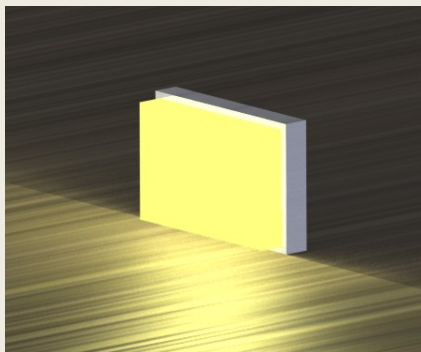
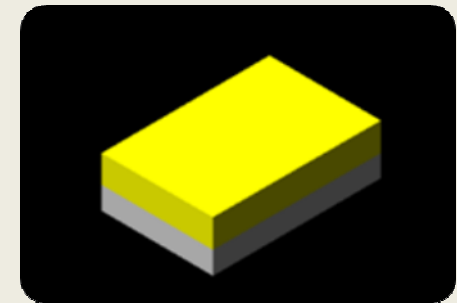


View angle : 60 degrees

Wide Beam Angle Product

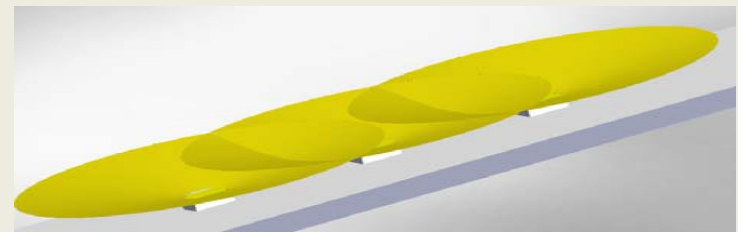
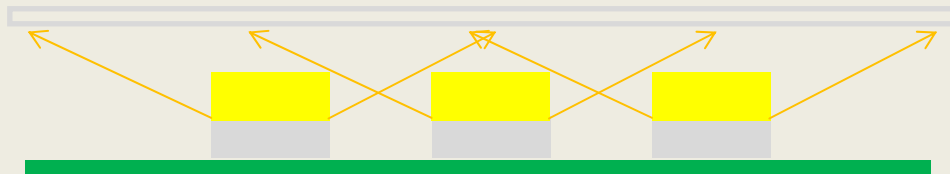
- Beam Angle
160 degree without lens
- Patented Structure
- Ultra compact profile ; 0.9 mm
- Uniform wide distribution beam angle
- Very suitable for Flat Light device, Back Light

AL-WH3020



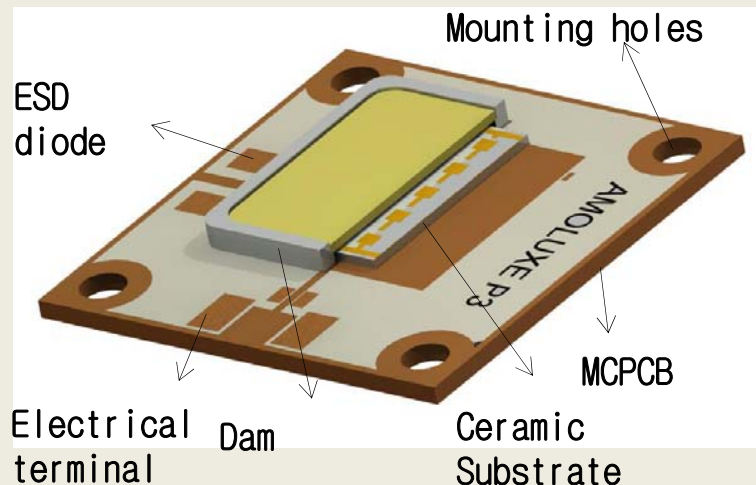
Application

- Application
 - Flat Panel Light Device
 - Light Bar
- Advantage
 - Hot Spot free due to wide viewing angle
 - Easy to design due to low profile



Multichip Package

- High Power & Thermal Management
 - 5 ~ 20 W with Specially Designed Material & Structure
 - Thermal Resistance : 3 °C/W
 - Cost effective assembly process
 - Application ; Very high luminous flux area
Flood light, Street light

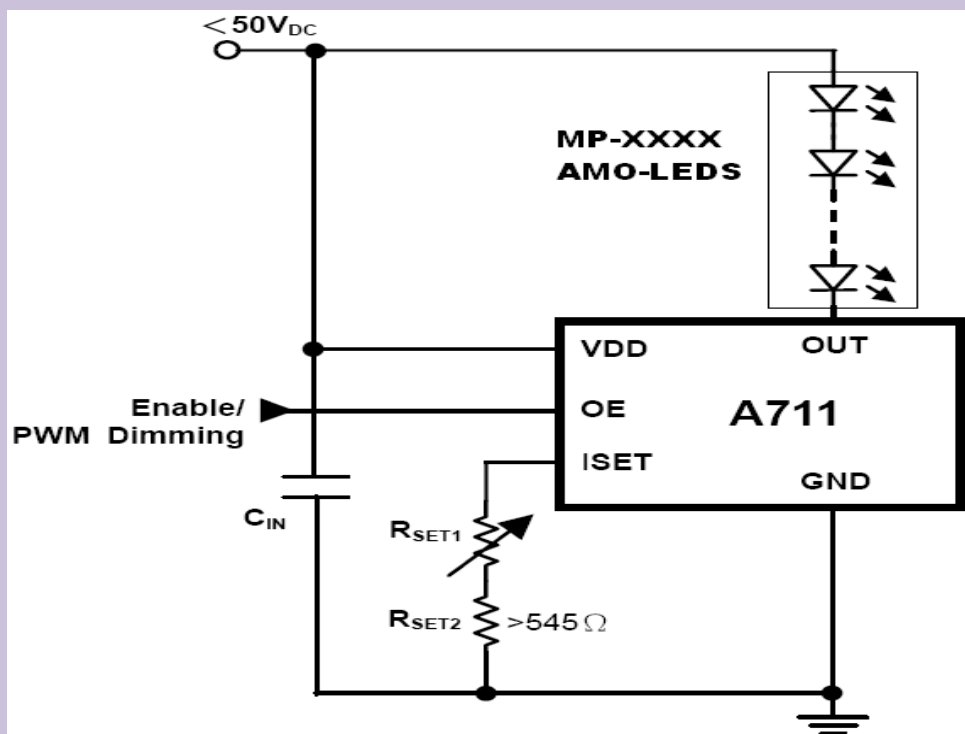


	MP-2216	MP-2822
Power Dissipation(W)	8	15
Forward Voltage(V)	11.3	17.9
Forward Current(mA)	700	1050
Junction Temp.(°C)	125	125
Thermal	3	3
Luminous Flux(lm)	720	1200

Circuit Guide

Ex) MP-2216 (8W)

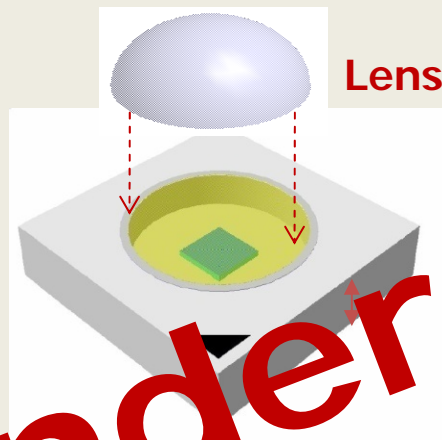
Constant Current Module



- More effective circuit Example)
- Constant Current IC
- Recommendation
Design as $V_{IN} - V_{LEDf} = < 1V$
- Easy control of constant current with R_{set} value

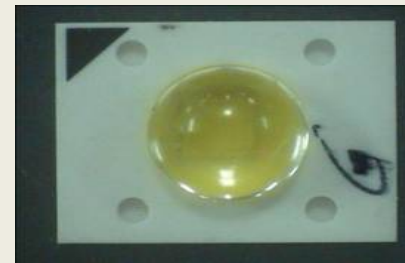
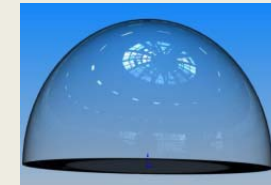
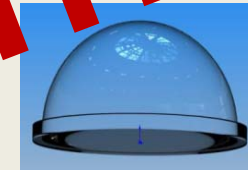
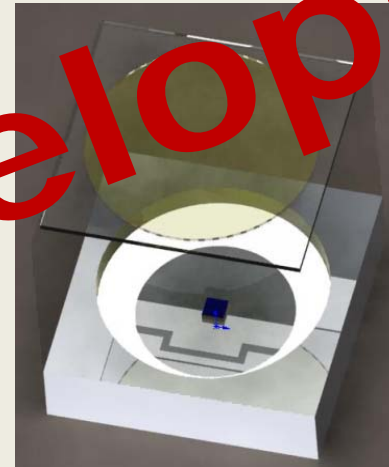
Very Narrow Beam Angle Product

- Reflector/Lens Combined Structure
- 30 ° beam angle with compact structure



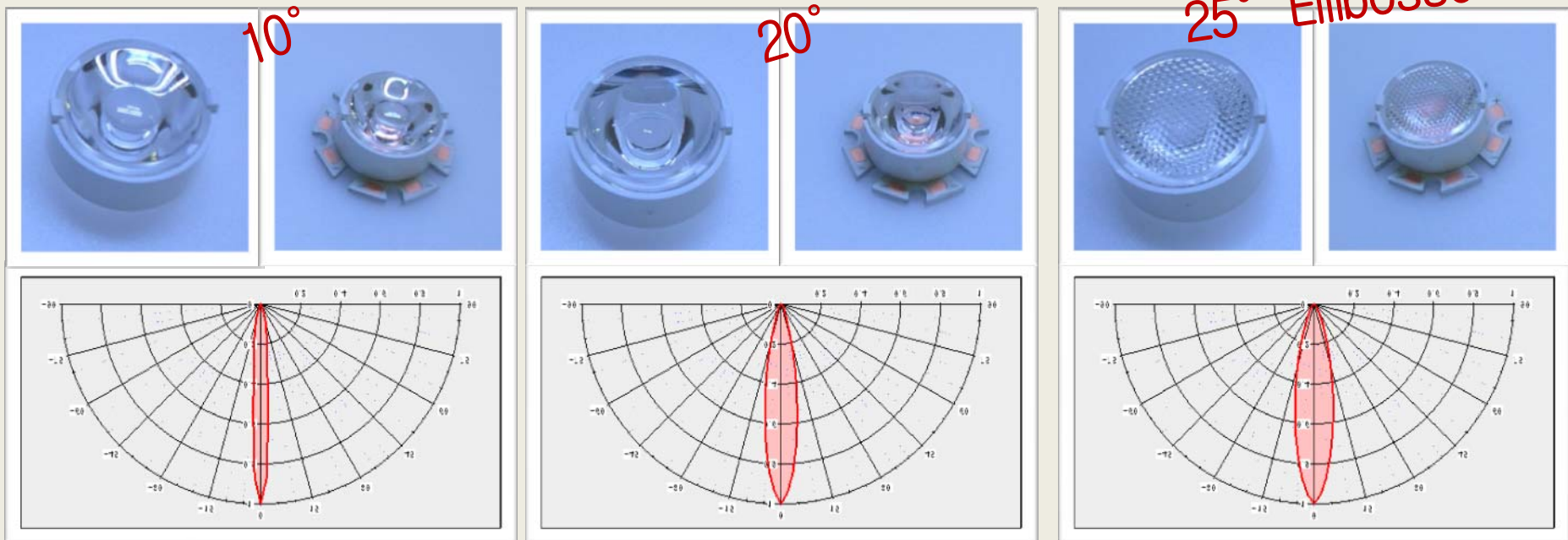
Lens attached into Cavity

Overall thickness
2 ~ 2.5mm



Optic

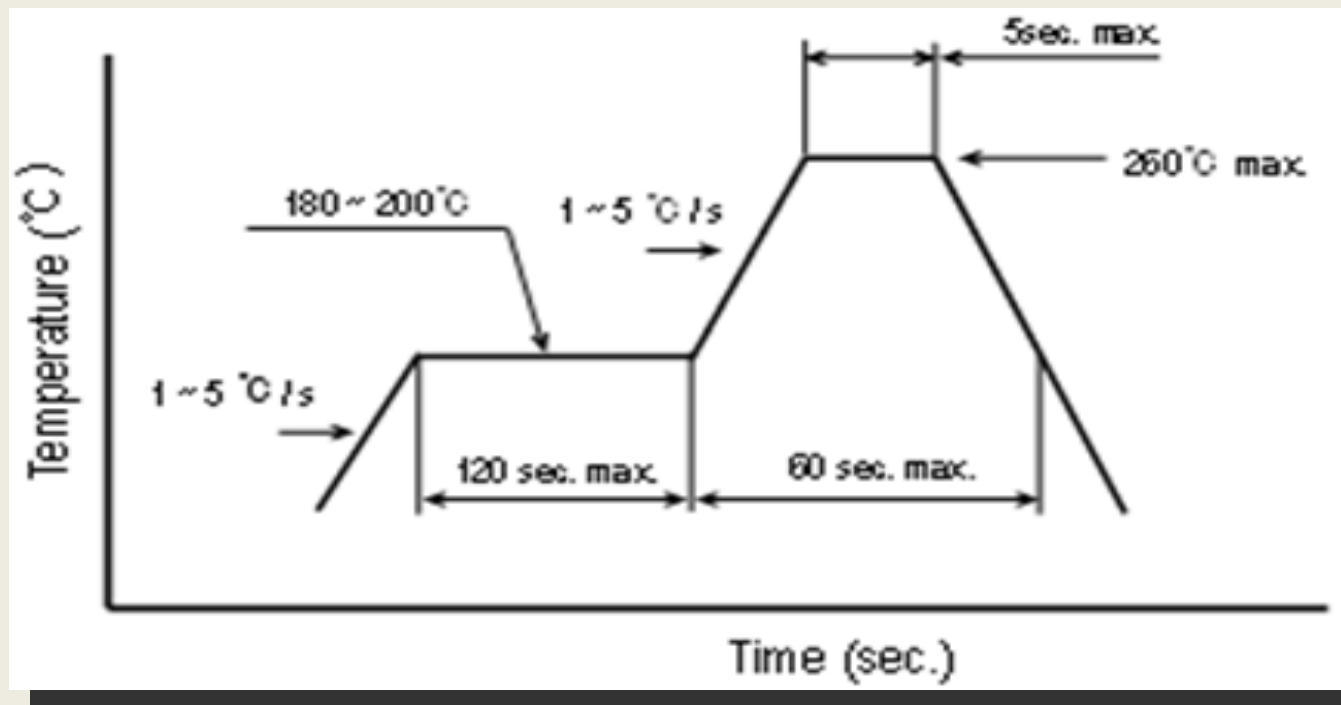
- Secondary Lens : Narrow angle for light devices
 - 10, 15, 20, 25, 30, 40 degree Distribution angle
 - Compact Size (Φ 21.0 x 10.0 mm)
 - 95% efficiency



Handling Guide

- **SMD Soldering**

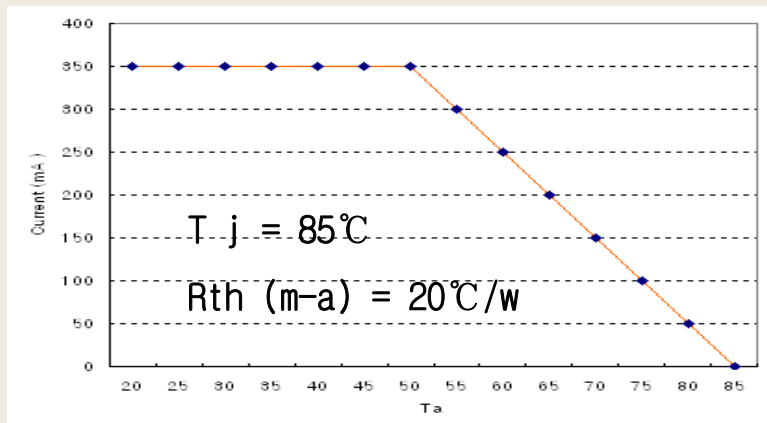
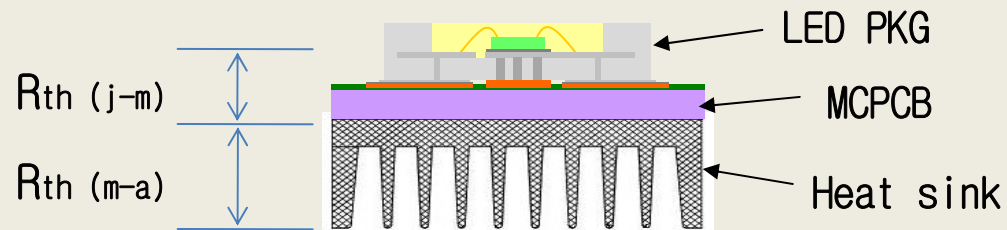
This ceramic LED should be reflow soldered to MCPCB or other board with the following condition.



Handling Guide

- Heat Sink Selection Guide

- $$T_j = T_a + ((V_f * I) * R_{th(m-a)}) + ((V_f * I) * R_{th(j-m)})$$



Current vs Ambient Temperature

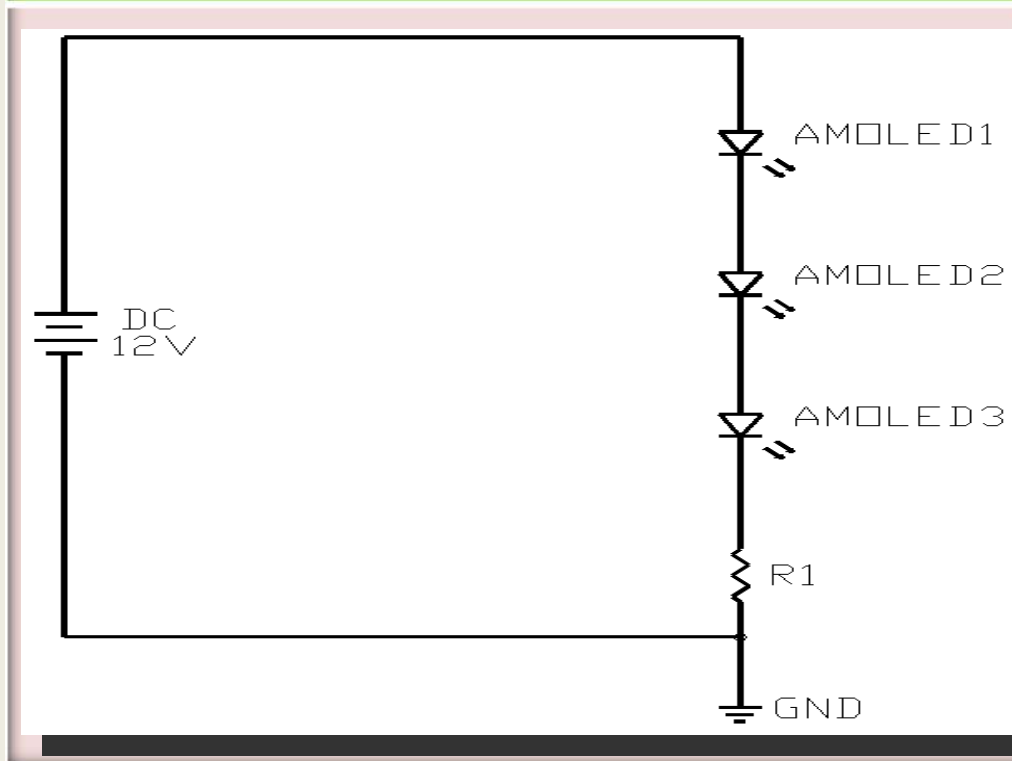
Example)

- AL-WH9070 ($R_{th} : 10^\circ\text{C/W}$)
- R_{th} of MCPCB + Heat sink : 20°C/W
- To keep T_j below 85°C ,
Refer to the current curve

Handling Guide

- Circuit Recommendation

1) DC with resistor (Serial)



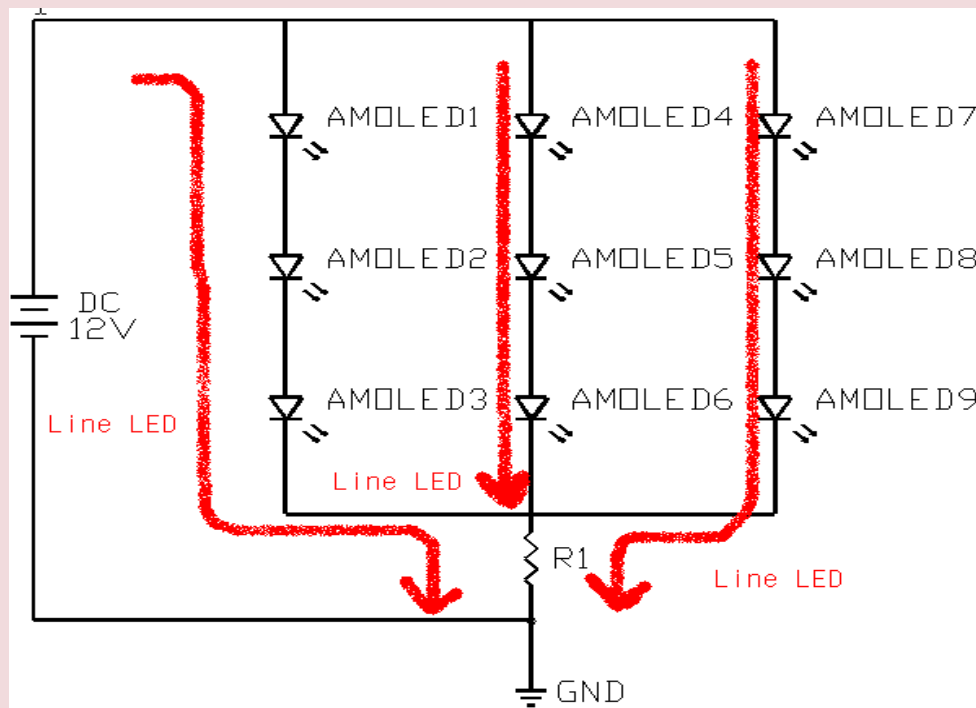
Example)

- $V_{IN} = \text{DC } 12\text{V}$
- $I_{LED} = 100\text{mA}$
- $V_{LEDf} = 3.4\text{V} \times 3 = 10.2\text{V}$
- $I_{LED} = (12\text{V} - 10.2\text{V})/R1$
- $R1 = 18\Omega$

Handling Guide

- Circuit Recommendation

2) DC with resistor (Serial + Parallel)



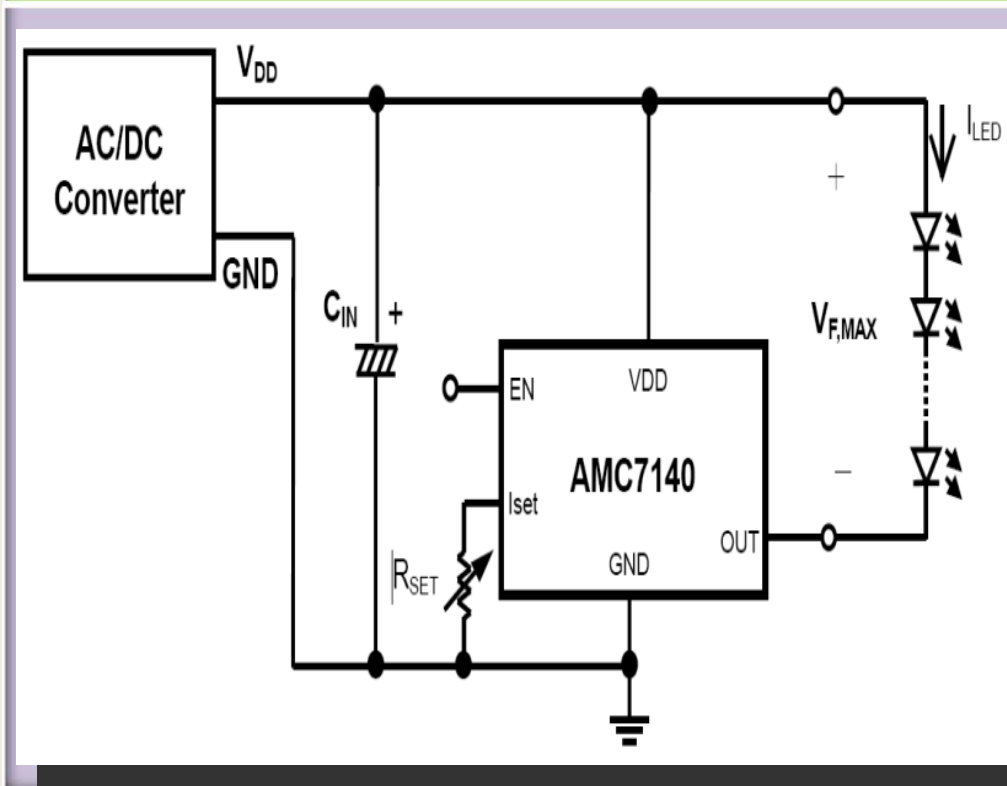
Example)

- $V_{IN} = \text{DC } 12\text{V}$
- $I_{LED} = 30\text{mA} / \text{line}$
- $V_{LEDf} = 3.4\text{V} \times 3 = 10.2\text{V}$
- $I_{LED} = (12\text{V} - 10.2\text{V})/R1$
- $R1 = 20 \Omega$

Handling Guide

- Circuit Recommendation

3) Constant Current Module

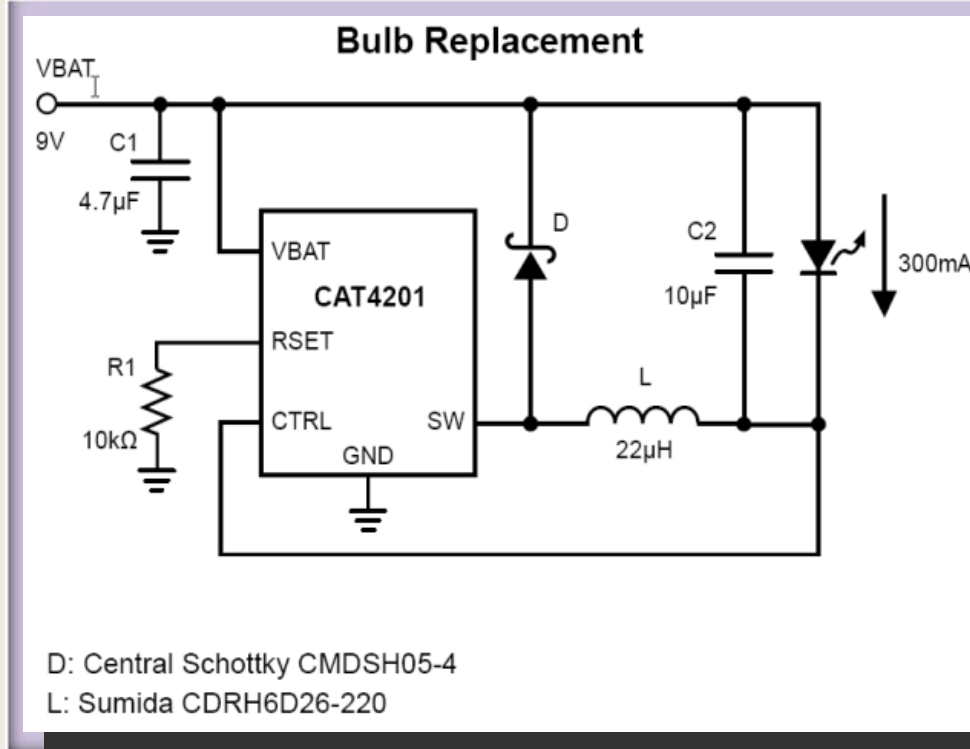


- More effective circuit Example)
- Constant Current IC
- Recommendation
Design as $V_{IN} - V_{LEDf} = < 1V$
- Easy control of constant current with R_{set} value

Handling Guide

- Circuit Recommendation

4) DC/DC Converter #1



In case of $V_{IN} > V_{LEDf}$
[Step down(Buck) Converter]

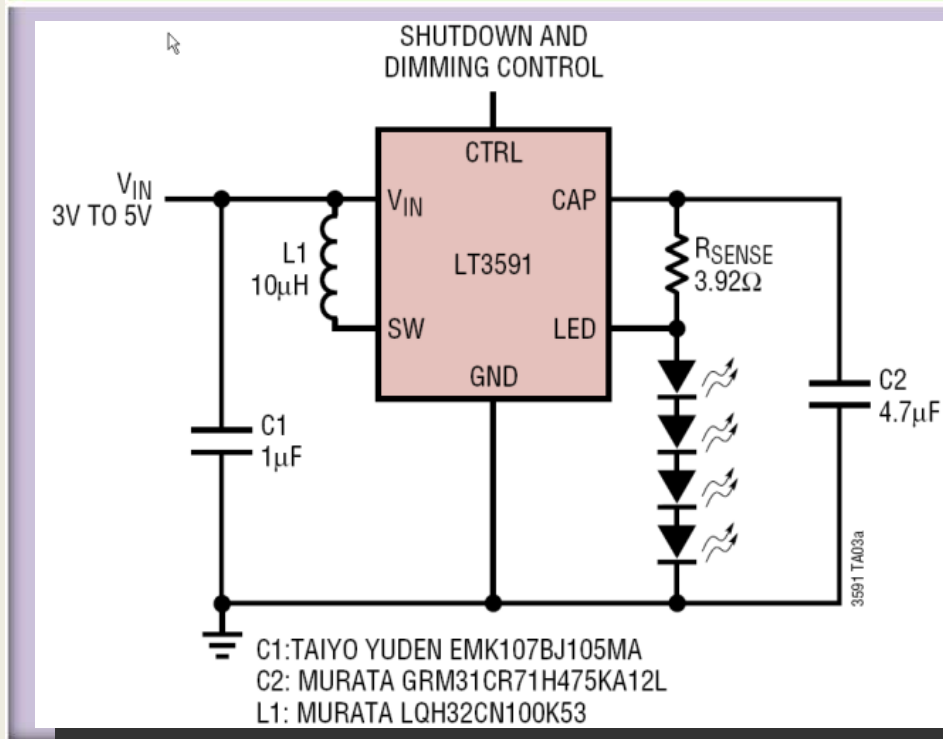
Example)

- Input Voltage = 9V
- Output Voltage = $3.4V_{LEDf}$
- Output Current = 300mA

Handling Guide

- Circuit Recommendation

5) DC/DC Converter #2



In case of $V_{IN} < V_{LEDf}$
[Step up(Boost) Converter]

Example)

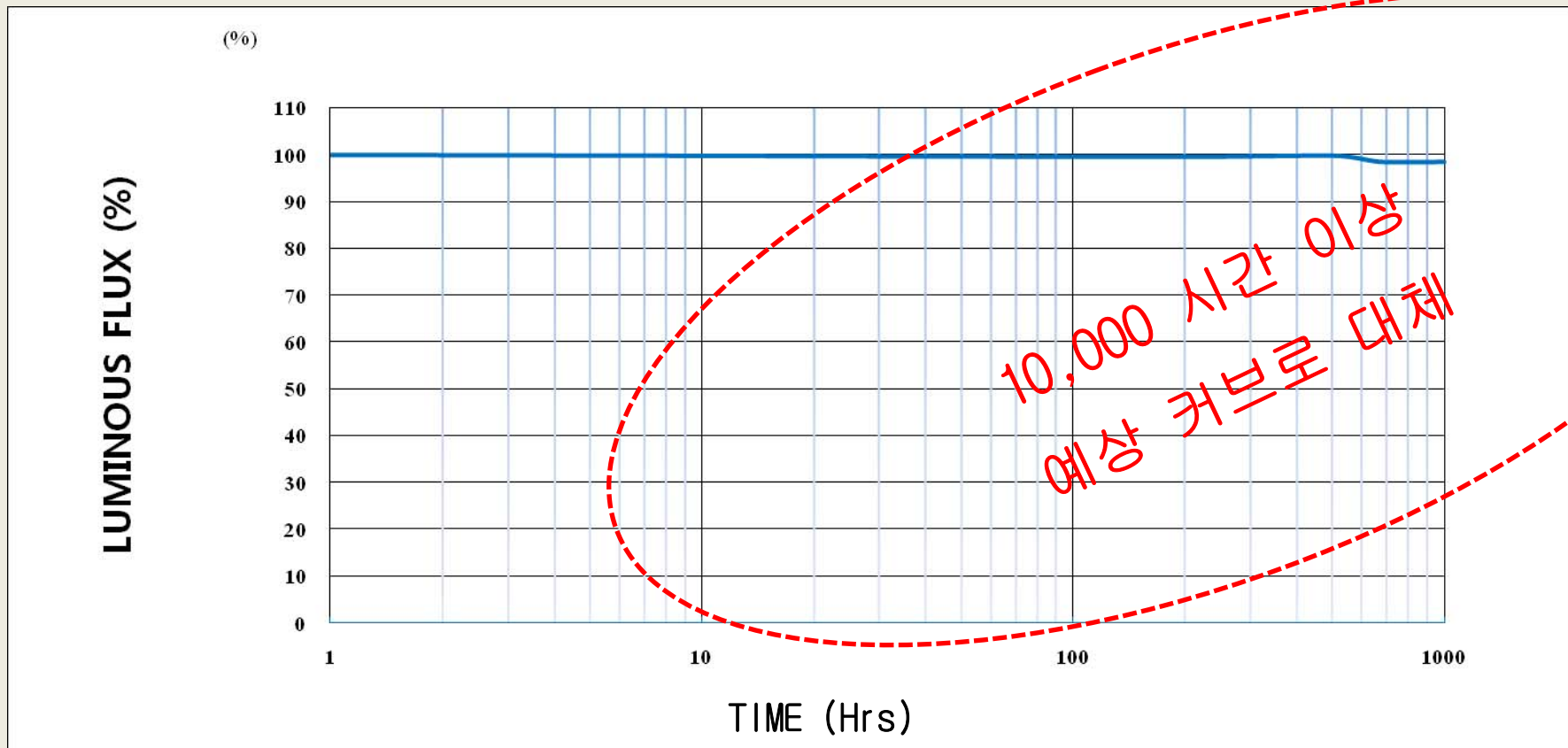
- Input Voltage = 3V~5V
- Output Voltage = $13.6V_{LEDf}$
- Output Current = 50mA

Reliability Test

Test Item	Test Condition
Life time	T amb= 25°C , I _F =700mA, 1000Hrs
Temperature Humidity Bios	T amb= 60°C /RH=90%, I _F =500mA, 1000Hrs
High Temp. Operating Life	T amb= 85°C , I _F =400mA, 1000Hrs
High Temp. Storage	T amb= 100°C , 1000Hrs
Low Temp. Storage	T amb= -40°C , 1000Hrs
Thermal Shock	T amb= -40°C ~ 110°C , 200 cycles (dwell : 20min, temp. transition : 20sec)
ESD	1,2,3,4,5,6KV discharge (3time/3sec : forward/reverse)

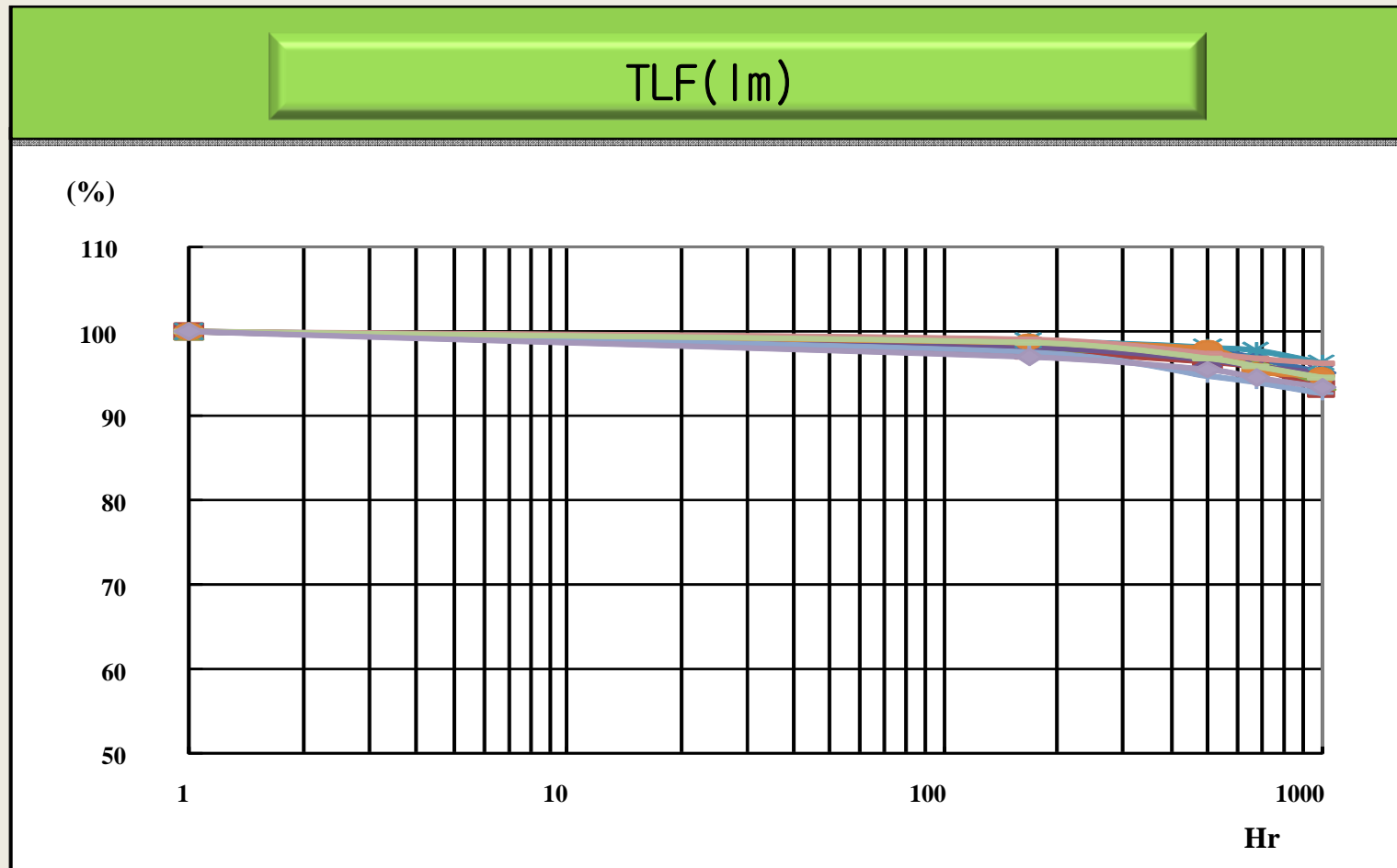
Life Time

- Room Temperature Operating Life Time Test Condition



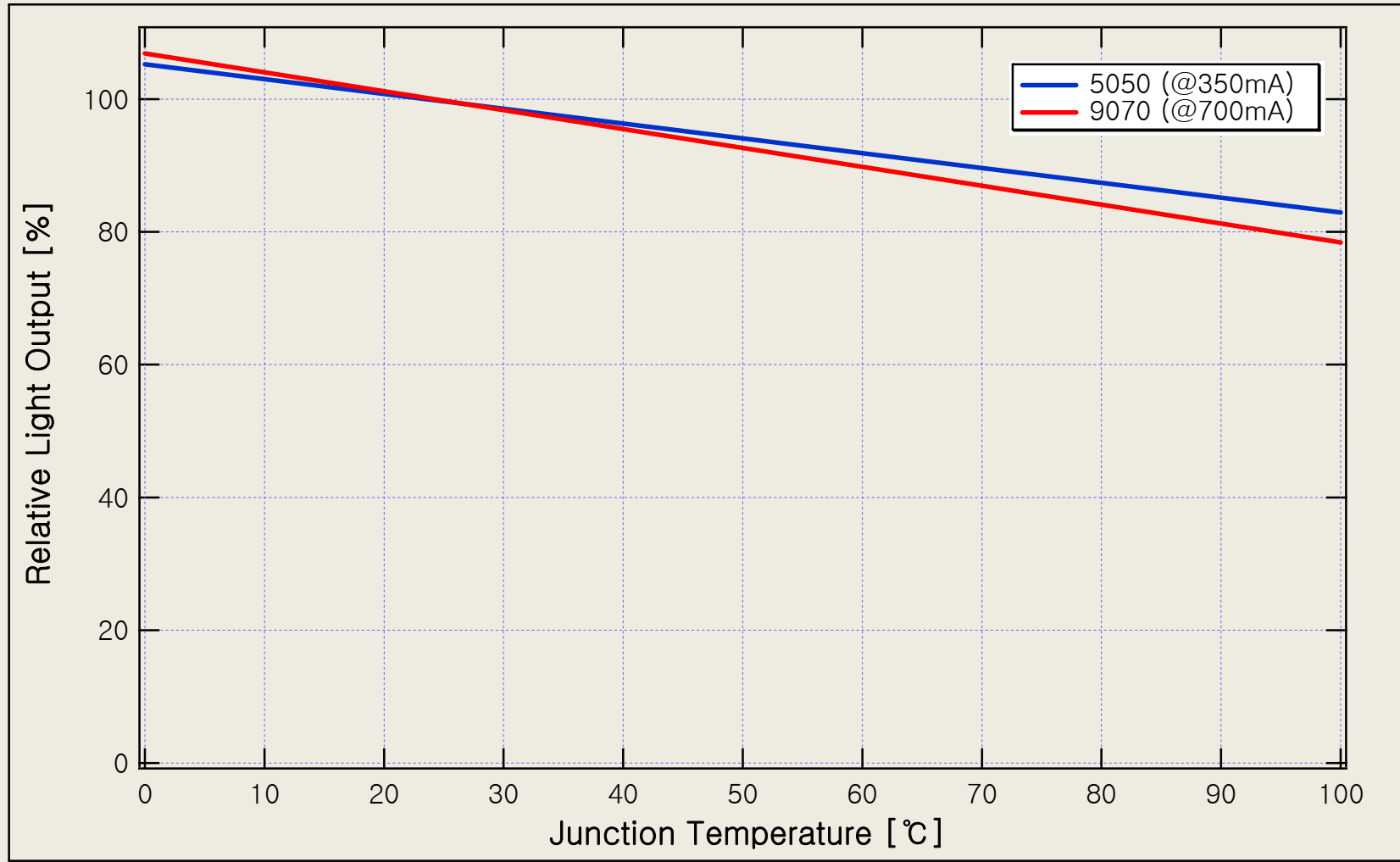
Ambient Temp. : 25 °C, Operating Current : 700mA

Temperature/Humidity



Bios $T_{amb} = 60^{\circ}\text{C}$ /RH= 90%, $I_F = 500\text{mA}$, 1000Hrs

Degradation with Junction Temperature



Current with Ambient Temperature

